

Microscopy and tomography for detecting semiconductor defects.

Jong Ho Won

Department of Chemistry, Kookmin University

ballnet09@kookmin.ac.kr

A few nano-processes are used to manufacture semiconductors, and 3D stacking technology has been introduced to increase the degree of integration. The rapid development of the level of integration is making semiconductor production more difficult and lowering the yield. The development of defect inspection technology is required to increase the yield and quality of semiconductor production. A light source with an extremely short wavelength is necessary to check defects on the level of a few nanometers or less. In addition, for multi-axis measurement of semiconductors stacked in 3D, a virtual 3D volume should be created. In this seminar, we will discuss about the microscopic inspection method that can measure defects of several nanometers or less and tomography with programming for the creation of 3D virtual volumes.